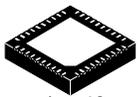


# MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

ON Semiconductor®

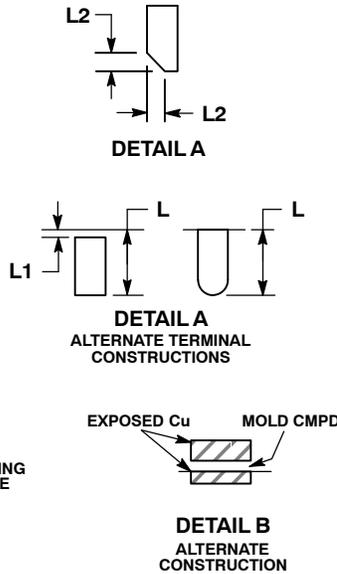
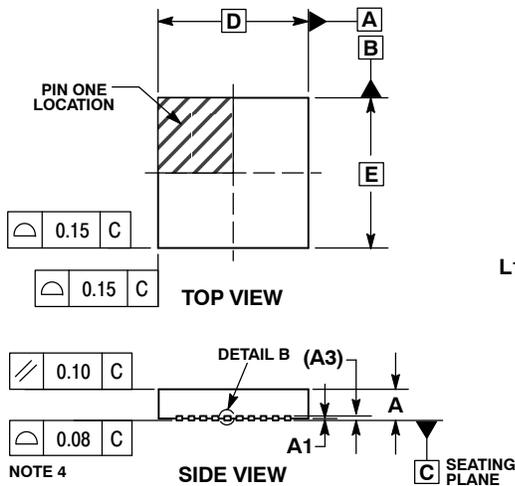


1 40

SCALE 2:1

QFN40 5x5, 0.4P  
CASE 485CR  
ISSUE C

DATE 27 AUG 2013

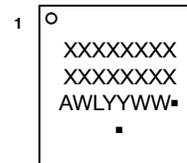


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSIONS: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30mm FROM THE TERMINAL TIP.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

MILLIMETERS		
DIM	MIN	MAX
A	0.80	1.00
A1	---	0.05
A3	0.20	REF
b	0.15	0.25
D	5.00 BSC	
D2	3.40	3.60
E	5.00 BSC	
E2	3.40	3.60
e	0.40 BSC	
L	0.30	0.50
L1	---	0.15
L2	0.12 REF	

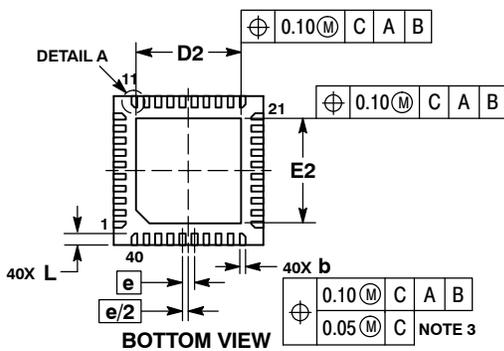
**GENERIC MARKING DIAGRAM\***



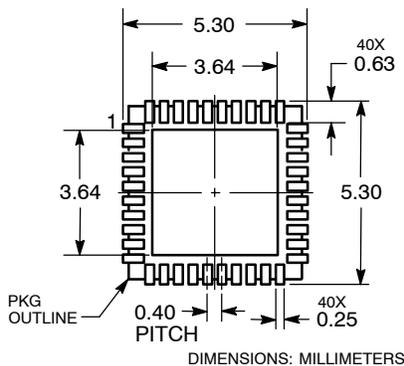
- XXXXXX = Specific Device Code
- A = Assembly Location
- WL = Wafer Lot
- YY = Year
- WW = Work Week
- = Pb-Free Package

(Note: Microdot may be in either location)

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.



**RECOMMENDED SOLDERING FOOTPRINT**



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<b>STATUS:</b>	ON SEMICONDUCTOR STANDARD	
<b>NEW STANDARD:</b>		
<b>DESCRIPTION:</b>	QFN40, 5x5, 0.4P	<b>PAGE 1 OF 2</b>

